

Date Created : 2008/08/06
Date Issued On : 2008/08/26
PCN# : Q3083205

DESIGN/PROCESS CHANGE NOTIFICATION -- FINAL

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

Updated process quality documentation, such as FMEAs and Control Plans, are available for viewing upon request.

If you have any questions concerning this change, please contact:

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Implementation of change:
Expected 1st Device Shipment Date: 2008/12/01

Earliest Year/Work Week of Changed Product: 0849

Change Type Description: Alternate Assembly Site Location / Qualification, Die Revision

Description of Change (From): Selected Tiny Logic 6-lead ULP/ULP-A devices manufactured on South Portlands FS35C Fab process line and assembled in MicroPak at Hana or ASEM.

Description of Change (To): The same design schematics are used but the die will be revised to add bond pad over active layer. For MicroPak package, Fairchild Malaysia (FSPM) will be added as an additional assembly location.

Reason for Change : Increase manufacturing capacity. Additionally, for the MicroPak package, to reduce the risk of single source supplier for BT substrate as multiple suppliers exist for the leadframes.

Qual/REL Plan Numbers : Q20080092

Qualification :

Attached are the reliability test results to qualify this change for the associated silicon and assembly sites.

Results/Discussion for Qual Plan Number Q20080092

Test: (Autoclave)			
Lot	Device	96-HOURS	Failure Code
Q20080092AAACL	NC7SZ125L6X	0/77	
Q20080092ABACL	NC7SZ125L6X	0/77	
Q20080092BAACL	NC7SZ125P5X	0/77	
Q20080092BBACL	NC7SZ125P5X	0/77	

Q20080092CAACLV	NC7SZ08P5X	0/77	
Test: (High Temperature Storage Life)			
Lot	Device	168-HOURS	1000-HOURS
Q20080092AAHTSL	NC7SZ125L6X	0/77	
Q20080092AAHTSL	NC7SZ125L6X		0/77
Q20080092ABHTSL	NC7SZ125L6X	0/77	
Q20080092ABHTSL	NC7SZ125L6X		0/77
Q20080092BAHTSL	NC7SZ125P5X	0/77	
Q20080092BAHTSL	NC7SZ125P5X		0/77
Q20080092BBHTSL	NC7SZ125P5X	0/77	
Q20080092BBHTSL	NC7SZ125P5X		0/77
Q20080092CAHTSL	NC7SZ08P5X	0/77	
Q20080092CAHTSL	NC7SZ08P5X		0/77
Test: (Static Op Life)			
Lot	Device	168-HOURS	1000-HOURS
Q20080092AASOPL1	NC7SZ125L6X	0/77	
Q20080092AASOPL1	NC7SZ125L6X		0/77
Q20080092ABSOPL1	NC7SZ125L6X	0/77	
Q20080092ABSOPL1	NC7SZ125L6X		0/77
Q20080092BASOPL1	NC7SZ125P5X	0/77	
Q20080092BASOPL1	NC7SZ125P5X		0/77
Q20080092BBSOPL1	NC7SZ125P5X	0/77	
Q20080092BBSOPL1	NC7SZ125P5X		0/77
Q20080092CASOPL1	NC7SZ08P5X	0/77	
Q20080092CASOPL1	NC7SZ08P5X		0/77
Test: -65C, 150C (Temperature Cycle)			
Lot	Device	500-CYCLES	Failure Code
Q20080092AATMCL1	NC7SZ125L6X	0/77	
Q20080092ABTMCL1	NC7SZ125L6X	0/77	
Q20080092BATMCL1	NC7SZ125P5X	0/77	
Q20080092BBTMCL1	NC7SZ125P5X	0/77	
Q20080092CATMCL1	NC7SZ08P5X	0/77	
Test: 130C (Highly Accelerated Stress Test)			
Lot	Device	96-HOURS	Failure Code
Q20080092AAHAST1	NC7SZ125L6X	0/45	
Q20080092ABHAST1	NC7SZ125L6X	0/45	
Q20080092BAHAST1	NC7SZ125P5X	0/45	
Q20080092BBHAST1	NC7SZ125P5X	0/45	
Q20080092CAHAST1	NC7SZ08P5X	0/45	
Test: MSL(1), PKG(Small), PeakTemp(260c), Cycles(3) (Precondition)			
Lot	Device	Results	Failure Code
Q20080092AAPCNL1A	NC7SZ125L6X	0/276	
Q20080092ABPCNL1A	NC7SZ125L6X	0/276	
Q20080092BAPCNL1A	NC7SZ125P5X	0/276	
Q20080092BBPCNL1A	NC7SZ125P5X	0/276	
Q20080092CAPCNL1A	NC7SZ08P5X	0/276	

Product Id Description :

Affected FSIDs :

NC7SV57L6X	NC7SV57L6X_F087	NC7SV58L6X
NC7SV58L6X_F087		